

Title (en)
INTEGRATED DEVICE COMPRISING HIGH DENSITY INTERCONNECTS AND REDISTRIBUTION LAYERS

Title (de)
INTEGRIERTE VORRICHTUNG MIT HOCHDICHTEN VERBINDUNGEN UND UMVERTEILUNGSSCHICHTEN

Title (fr)
DISPOSITIF INTÉGRÉ COMPRENANT DES ÉLÉMENTS D'INTERCONNEXION À HAUTE DENSITÉ ET DES COUCHES DE REDISTRIBUTION

Publication
EP 3114707 A1 20170111 (EN)

Application
EP 15710373 A 20150304

Priority
• US 201414196817 A 20140304
• US 2015018784 W 20150304

Abstract (en)
[origin: US2015255416A1] Some novel features pertain to an integrated device (e.g., integrated package) that includes a base portion for the integrated device, a first die coupled to a first surface of the base portion, and an underfill between the first die and the base portion. The base portion includes a dielectric layer, and a set of redistribution metal layers. In some implementations, the integrated device further includes an encapsulation material that encapsulates the first die. In some implementations, the integrated device further includes a second die coupled to the first surface of the base portion. In some implementations, the integrated device further includes a set of interconnects on the base portion, the set of interconnects electrically coupling the first die and the second die. In some implementations, the first die includes a first set of interconnect pillars and the second die includes a second set of interconnect pillars.

IPC 8 full level
H01L 23/538 (2006.01); **H01L 21/56** (2006.01)

CPC (source: CN EP US)
H01L 23/3107 (2013.01 - CN US); **H01L 23/3157** (2013.01 - CN US); **H01L 23/5389** (2013.01 - CN EP US); **H01L 24/19** (2013.01 - CN EP US); **H01L 24/24** (2013.01 - CN EP US); **H01L 24/25** (2013.01 - CN US); **H01L 24/82** (2013.01 - CN EP US); **H01L 24/96** (2013.01 - CN EP US); **H01L 21/568** (2013.01 - CN EP US); **H01L 2224/0401** (2013.01 - CN EP US); **H01L 2224/04105** (2013.01 - CN EP US); **H01L 2224/05572** (2013.01 - CN EP US); **H01L 2224/12105** (2013.01 - CN EP US); **H01L 2224/131** (2013.01 - CN EP US); **H01L 2224/24137** (2013.01 - CN EP US); **H01L 2924/014** (2013.01 - CN); **H01L 2924/14335** (2013.01 - CN EP US); **H01L 2924/1434** (2013.01 - CN EP US); **H01L 2924/1815** (2013.01 - CN US)

Citation (search report)
See references of WO 2015134638A1

Designated contracting state (EPC)
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Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
US 2015255416 A1 20150910; **US 9230936 B2 20160105**; CN 106068558 A 20161102; EP 3114707 A1 20170111; JP 2017507495 A 20170316; WO 2015134638 A1 20150911

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US 201414196817 A 20140304; CN 201580011603 A 20150304; EP 15710373 A 20150304; JP 2016555342 A 20150304; US 2015018784 W 20150304